

Packaging decapsulation

Advanced mold decapping technology that does not damage inside

Laser decapsulation + chemical decapsulation + observation

Laser openers or acids and organic chemicals are used to melt the packaging of electronic components and observe the bonding wire bonding condition and the wiring condition in the chip.

In addition to the technology of cross-sectional polishing, a wide variety of samples can be made for analysis.

1 Laser decapsulation

IC is removed by laser. In addition to shortening processing time, damage to the sample can be significantly reduced.



2 Decapsulation with chemical

There are two ways to use acids and organic solvents.

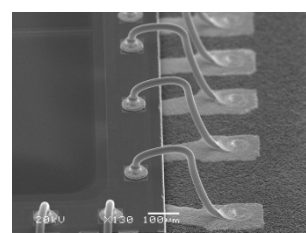
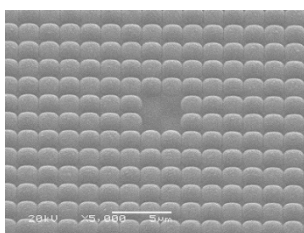
In the case the acid is used, fuming nitric acid or sulfuric acid is used, but using acid has a risk of damaging to the contents of the package, so that it is also possible to adjust the solubility by changing the chemical solution into an organic solvent.

3 Observation

The decapsulated sample is observed with high accuracy by using SEM-EDX (Scanning Electron-Microscope) to identify constituent elements.



Example: SEM Observation Images



We pay close attention to the details of consultations and requests with the first priority on strict adherence. In particular, a confidentiality agreement shall be entered into in the event of a request.